

## Product Summary

B250AF/B260AF

V <sub>RRM</sub> (V)	I <sub>o</sub> (A)	V <sub>F(MAX)</sub> (V) @ +25°C	I <sub>R(MAX)</sub> (mA) @ +25°C
50	2	0.65	0.10
60	2	0.65	0.20

## Description and Applications

The Schottky rectifier providing low V<sub>F</sub> and excellent reverse leakage stability at high temperatures, this device is ideal for use in general rectification applications such as:

- Boost Diode
- Blocking Diode
- Recirculating Diode

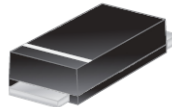
## Features and Benefits

- Reduced Low Forward Voltage Drop (V<sub>F</sub>); Better Efficiency and Cooler Operation
- Reduced High-Temperature Reverse Leakage; Increased Reliability against Thermal Runaway Failure in High Temperature Operation
- **Lead-Free Finish; RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**

## Mechanical Data

- Case: SMAF
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (Ⓜ3)
- Polarity: Cathode Band
- Weight: 0.036 grams (Approximate)

SMAF



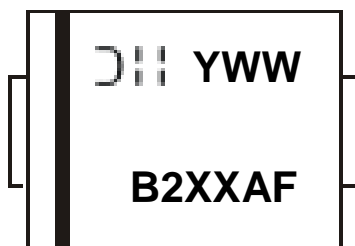
Top View

## Ordering Information (Note 4)

Part Number	Case	Packaging
B250AF-13	SMAF	10,000/Tape & Reel
B260AF-13	SMAF	10,000/Tape & Reel

- Notes:
1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

## Marking Information



B2XXAF = Product Type Marking Code, ex: B250AF  
 DII = Manufacturers' Code Marking  
 YWW = Date Code Marking  
 Y = Last Digit of Year (ex: 7 for 2017)  
 WW = Week Code (01 to 53)

**Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.  
For capacitive load, derate current by 20%.

Characteristic	Symbol	B250AF	B260AF	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	50	60	V
Working Peak Reverse Voltage	V <sub>RWM</sub>			
DC Blocking Voltage	V <sub>RM</sub>			
Average Rectified Output Current	I <sub>O</sub>	2		A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I <sub>FSM</sub>	50		A

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance Junction to Ambient (Note 5)	R <sub>θJA</sub>	95	°C/W
Typical Thermal Resistance Junction to Case (Note 5)	R <sub>θJC</sub>	45	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Forward Voltage Drop	V <sub>F</sub>	—	0.55	0.65	V	I <sub>F</sub> = 2A, T <sub>J</sub> = +25°C I <sub>F</sub> = 2A, T <sub>J</sub> = +125°C
Leakage Current (Note 6)	I <sub>R</sub>	—	0.015	0.10	mA	V <sub>R</sub> = 50V, T <sub>J</sub> = +25°C V <sub>R</sub> = 60V, T <sub>J</sub> = +25°C V <sub>R</sub> = 60V, T <sub>J</sub> = +125°C
Typical Capacitance	C <sub>T</sub>	—	80	—	pF	V <sub>R</sub> = 4.0V, f = 1MHz

Notes: 5. Device mounted on FR-4 substrate, 0.4" x 0.5", 2oz, single-sided, PC boards with 0.2" x 0.25" copper pad.  
6. Short duration pulse test used to minimize self-heating effect.

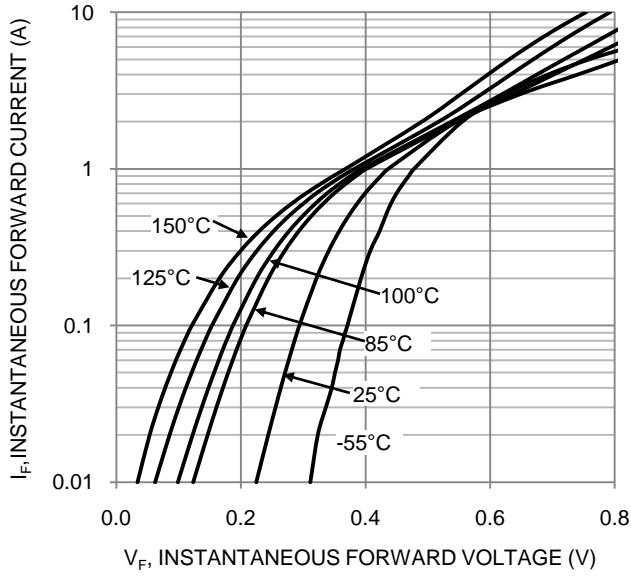


Figure 1. Typical Forward Characteristics

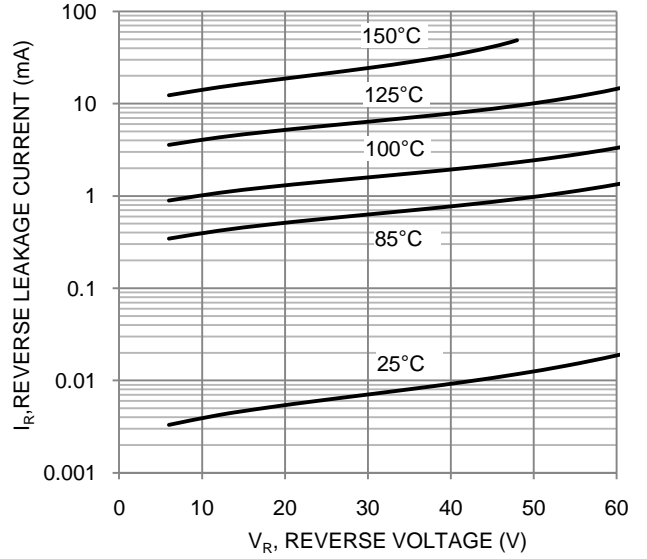


Figure 2. Typical Reverse Characteristics

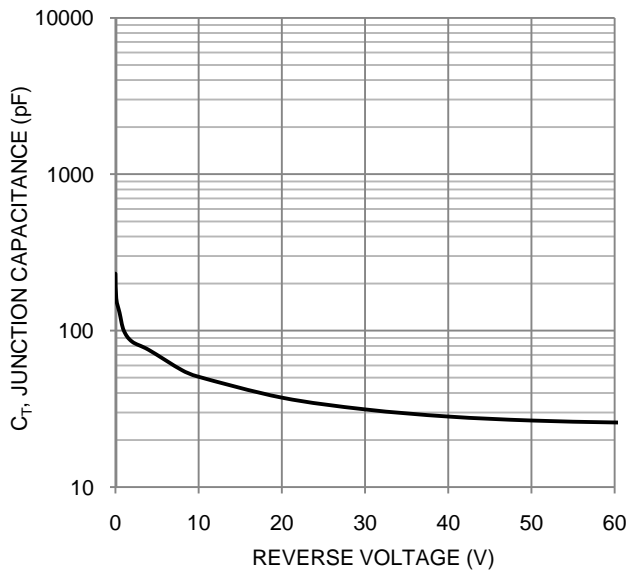


Figure 3. Typical Junction Capacitance

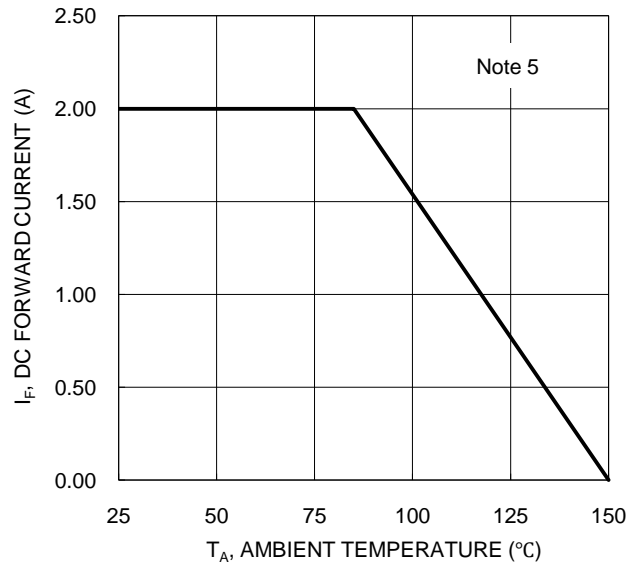
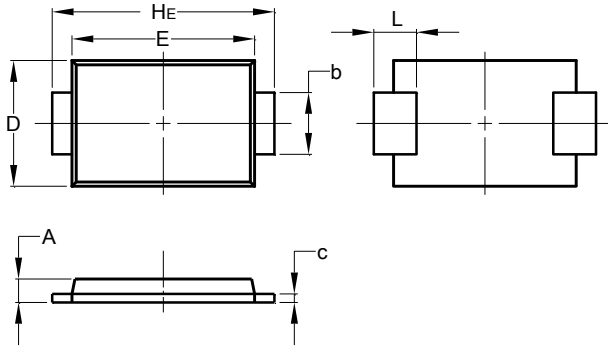


Figure 4. DC Forward Current Derating

## Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### SMAF

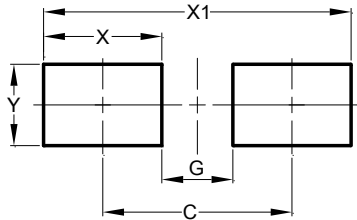


SMAF		
Dim	Min	Max
A	0.90	1.10
b	1.25	1.65
c	0.10	0.40
D	2.25	2.95
E	3.95	4.60
HE	4.80	5.60
L	0.50	1.50
All Dimensions in mm		

## Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

### SMAF



Dimensions	Value (in mm)
C	4.00
G	1.50
X	2.50
X1	6.50
Y	1.70

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